WHAT IS CLAIMED IS:

1. A method for treating an object with a laser comprising the steps of:

emitting a laser beam from a laser;

expanding said laser beam in a first direction;

removing a portion of said laser beam though a mask, said portion including at least edges of said expanded laser beam extending in said first direction; and

condensing said laser beam in a second direction orthogonal to said first direction in order to form a line-shaped laser beam on an object.

2. The method of claim 1 wherein the step of condensing said laser beam is done through a synthetic quartz lens.

3. The method of claim 1 wherein said laser is a pulse laser.

4. The method of claim 1 wherein said laser is an excimer laser.

5. The method of claim 1 wherein said object treated with said laser has a semiconducting or insulating surface thereon.

6. A method for treating an object with a laser comprising the steps of:

emitting a rectangular-shaped laser beam from a laser;

expanding said laser beam in a first direction;

removing a portion of said laser beam though a mask, said portion said portion including at least edges of said expanded laser beam extending in said first direction; and

condensing said laser beam in a second direction orthogonal to said first direction in order to form a line-shaped laser beam on an object.

7. The method of claim 6 wherein the step of condensing said laser beam is done through a synthetic quartz lens.

8. The method of claim 6 wherein said laser is a pulse laser.

9. The method of claim 6 wherein said laser is an excimer laser.

10. The method of claim 6 wherein said object treated with said laser has a semiconducting or insulating surface thereon.

11. A method for treating an object with a laser comprising the steps of:

emitting a laser beam from a laser;

expanding said laser beam in a first direction;

removing a portion of said laser beam through a mask, said portion including at least edges of said expanded laser beam extending in said first direction;

condensing said laser beam in a second direction orthogonal to said first direction in order to form a line-shaped laser beam on an object; and

changing the relative location of said object with respect to said line-shaped laser beam so that said object is scanned with said line-shaped laser beam.

12. The method of claim 11 wherein the step of condensing said laser beam is done through a synthetic quartz lens.

13. The method of claim 11 wherein said laser is a pulse laser.

14. The method of claim 11 wherein said laser is an excimer laser.

15. The method of claim 11 wherein said object treated with said laser has a semiconducting or insulating surface thereon.

16. The method of claim 11 wherein said object is scanned with said line-shaped laser beam in said second direction orthogonal to the first direction in which said laser beam is expanded.